Application No. 09/453,055 Amendment Accompanying RCE Docket No. 032405.027

IN THE CLAIMS:

Please amend Claims 2 and 19, as follows:

1. (Cancelled)

2. (Currently Amended) A method of forming a honeycomb sandwich composite panel [consisting essentially of] by a resin transfer molding process consisting of:

stacking a thermosetting sealing material on at least one side of a honeycomb core, said thermosetting sealing material having an adhesive property and being a resin film including glass microspheres;

stacking a dry fabric on said thermosetting sealing material;

hardening said sealing material by heating said sealing material and said dry fabric to the curing temperature of said sealing material and maintaining this temperature for a specified curing time period of said sealing material;

impregnating said dry fabric with a thermosetting resin while varying the temperature of said sealing material and said dry fabric to a resin impregnating temperature and maintaining this temperature for a specified period of time; and

hardening the resin impregnated into said dry fabric by heating said sealing material and said dry fabric to the curing temperature of said thermosetting resin and hotpressing them for a specified period of time.

3-9 (Cancelled)

10. ((Previously Amended) The method of forming the honeycomb sandwich composite

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said sealing material is a laminated film formed by laminating a plurality of thermosetting resin films.

11-15 (Cancelled)

16. (Previously Added) The method of forming a honeycomb sandwich composite panel according to Claim 2, wherein:

said curing temperature of said sealing material is about 1205°C, and said specified curing time period is about 13010 minutes.

17. (Previously Added) The method of forming a honeycomb sandwich composite panel according to Claim 2, wherein:

said sealing material is a laminated film formed by laminating a plurality of thermosetting resin films including said glass microspheres.

18. (Previously Added) The method of forming a honeycomb sandwich composite panel according to Claim 2, wherein:

said sealing material is a laminated film formed of at least two thermosetting adhesive films and a thermosetting resin film placed between the thermosetting adhesive films, with glass microspheres mixed in the thermosetting resin film.

19. (Currently Amended) A method of forming a honeycomb sandwich composite panel by a resin transfer molding process consisting essentially of:

stacking a plurality of thermosetting sealing materials on at least one of sides of a honeycomb; said each of thermosetting materials having an adhesive property, and including at least one layer of short fibers and non-woven fabric of glues glass;

stacking a dry fabric on said thermosetting sealing materials;

hardening said sealing materials by heating to a sufficient temperature and maintaining this temperature for a specified period of time; impregnating the dry fabric with a thermosetting resin and hardening the resin impregnated into said dry fabric by heating said resin and said fabric to the curing temperature of said thermosetting resin and hot-pressing them for a specified time period.

20. 21. (Currently Amended) The method of forming a honeycomb sandwich composite panel according to Claim 20 19, wherein,

a carrier material is provided between said plurality of thermosetting sealing materials.

21. 22. (Currently Amended) The method of forming a honeycomb sandwich composite panel according to Claim 20 19, wherein

said thermosetting sealing material is a laminate of three layers, and includes at least one layer of short fibers or non-woven fabric of glass.

22. 23. (Currently Amended) The method of forming a honeycomb sandwich composite panel according to Claim 20 19, wherein:

said sealing material is hardened at a temperature lower than the curing temperature of the impregnating resin.

23. 24. (Currently Amended) The method of forming a honeycomb sandwich composite panel according to Claim 20 19, wherein:

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said curing temperature of said sealing material is about 120 \pm 5°C, and said specified curing time period is about 130 \pm 10 minutes.